IN THE CLAIMS:

Claim 4 has been amended herein. All of the pending claims 1 through 14 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Previously presented) A memory module, comprising:

a substrate;

at least two sites on said substrate, each of said at least two sites having mounted thereon a memory chip with substantially the same memory capacity, said memory chips providing a memory capacity for said memory module; and

at least one other site on said substrate for mounting at least one additional memory chip thereon, said at least one additional memory chip having a functional memory less than said memory capacity of said memory module.

2. (Previously presented) A memory module, comprising:

a substrate;

at least two sites on said substrate, each of said at least two sites having mounted thereon a memory chip with substantially the same memory capacity, said memory chips providing a memory capacity for said memory module; and

at least one other site on said substrate configured to accept either of at least two other memory chips of different sizes.

3. (Previously presented) A memory module, comprising:

a substrate having a plurality of memory chips mounted thereon; and

a programmable device adapted to reroute input and output paths to and from said plurality of memory chips to bypass nonfunctional memory in at least one of said plurality of memory chips, extending to one or more additional locations on said substrate and configured to incorporate functional memory of one or more additional chips disposed at said one or more additional locations and selected in relation to an amount of detected nonfunctional memory of said plurality of memory chips on said substrate into said rerouted input and output paths.

4. (Currently amended) The memory module of claim 3, further comprising at least one additional memory chip mounted on at least one of said one or more additional locations, operably coupled to said programmable device and providing functional memory in an amount equivalent to or greater than said nonfunctional memory.

5. (Previously presented) The memory module of claim 4, wherein said at least one additional memory chip contains at least some nonfunctional memory.

6. (Previously presented) The memory module of claim 4, wherein said at least one additional memory chip comprises at least two memory chips having different memory capacity and being placed at different additional locations.

7. (Previously presented) The memory module of claim 3, wherein said programmable device comprises an EEPROM.

8. (Previously presented) A memory module comprising:

a plurality of chips mounted to a substrate, said plurality of chips collectively exhibiting an amount of detected nonfunctional memory exceeding a memory capacity of any one chip of said plurality; and

at least one additional memory chip mounted to said substrate providing an amount of functional memory selected in relation to and equal to or greater than said amount of detected nonfunctional memory.

9. (Original) The module of claim 8, wherein said at least one additional memory chip comprises at least two memory chips having different amounts of functional memory.

10. (Previously presented) The memory module of claim 5, wherein said at least one additional memory chip contains an amount of functional memory substantially equal to an amount of nonfunctional memory in said at least one of said plurality of memory chips.

11. (Previously presented) The memory module of claim 4, wherein said at least one additional memory chip contains an amount of functional memory substantially equal to an amount of nonfunctional memory in said at least one of said plurality of memory chips.

12. (Previously presented) The memory module of claim 8, wherein said at least one additional memory chip provides an amount of functional memory substantially equal to said amount of nonfunctional memory collectively exhibited by said plurality of memory chips.

13. (Previously presented) The memory module of claim 8, wherein said at least one additional memory chip contains at least some nonfunctional memory.

14. (Previously presented) The memory module of claim 13, wherein said at least one additional memory chip provides an amount of functional memory substantially equal to said amount of nonfunctional memory collectively exhibited by said plurality of memory chips.